



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-10-10
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FDO7*0082BG6	A	BO2A	2014-10-10
Amount	UoM	Unit type	ST ECOPACK Grade	
77.50	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MDF valid for TL072BIYDT; TL072CD; TL082AIYDT; TL082BIYDT; TL082CD; TL082IYDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FDO7*0082BG6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	1.356	mg	supplier	die	Silicon (Si)	7440-21-3		1.332	mg	982301	17187
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	8112	142
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.006	mg	4425	77
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.007	mg	5162	90
Leadframe	Copper & its alloys	34.574	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.494	mg	997686	445084
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.016	mg	463	206
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.029	mg	839	374
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.032	mg	926	413
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	58	26
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	29	13
Die attach	Other inorganic materials	0.440	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.330	mg	750000	4258
Die attach				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.108	mg	245455	1394
Die attach				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.002	mg	4545	26
Bonding wire	Precious metals	0.066	mg	supplier	wire	Gold (Au)	7440-57-5		0.066	mg	1000000	852
encapsulation	Other inorganic materials	41.064	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.106	mg	99990	52981
encapsulation				supplier	mold compound	phenol resin	9003-35-4		2.053	mg	49995	26490
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.411	mg	10009	5303
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		32.850	mg	799971	423871
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		0.822	mg	20018	10606
encapsulation				supplier	mold compound	Brominated epoxy resin	40039-93-8		0.822	mg	20018	10606